



THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Jin et al.
Appl. No. : 09/178,249
Filed : October 23, 1998
Title : Integrated Circuit Dielectric ...

Art Unit : 2825
Examiner : Lee

Docket : TI-26111

RECEIVED
APR 25 2001
TECHNOLOGY CENTER 2800

Assistant Commissioner
for Patents
Box NonFee Amendment
Washington, DC 20231

MAILING CERTIFICATE	
I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Assistant Commissioner for Patents, Washington, DC 20231 today.	
<i>Gracia Sansom</i>	<i>4-19-2001</i>
Gracia Sansom	Date

AMENDMENT AND/OR ARGUMENT

Dear Sir:

In response to the Office Action mailed 01/19/01, applicants argue as follows.

REMARKS

Claims 1-7 are pending in the application; reexamination and reconsideration are hereby requested.

Claims 1-2, 4, and 6 were rejected as anticipated by Smith. The Examiner cited Smith column 31, lines 5-10.

Applicants reply that Smith column 31, lines 5-10 does not suggest flowing the vapor catalyst; rather, Smith uses closed chambers (Figs. 16A-19C). Indeed, Smith would likely add a vapor catalyst as noted in column 31, lines 5-10 by using a chamber as in Fig. 19C and described in column 27, lines 53-64. Consequently, Smith does not anticipate independent claim 1.

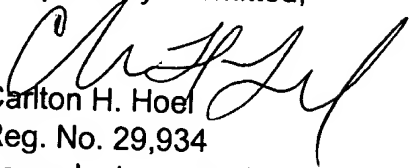
Claims 3, 5, and 7 were rejected as unpatentable over Smith in view of Radhakrishnan. The Examiner cited Radhakrishnan for a low temperature deposition system.

Applicants reply that Radhakrishnan is a gas-phase deposition system and does not suggest a catalyst.

Claim 4 was rejected as not supported by the specification. The Examiner cited the ammonia bubbling through a water solution.

Applicants reply that Fig. 1h and application page 6, last paragraph support the claim. Note that NH₄OH only exists in water solution.

Respectfully submitted,



Carlton H. Hoel

Reg. No. 29,934

Texas Instruments Incorporated

PO Box 655474, M/S 3999

Dallas, Texas 75265

972.917.4365